

# **General Description**

The WSD3050DN is the highest performance trench N-ch MOSFETs with extreme high cell density , which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The WSD3050DN meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

#### **Features**

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

# **Absolute Maximum Ratings**

## **Product Summery**

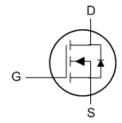
BVDSS	RDSON	ID
30V	7m $\Omega$	50A

# **Applications**

- High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch

## **DFN3X3-8 Pin Configuration**





	Rating			
Symbol	Parameter	10s	Steady State	Units
V <sub>DS</sub>	Drain-Source Voltage	3	30	V
V <sub>GS</sub>	Gate-Source Voltage	±	20	V
I <sub>D</sub> @T <sub>C</sub> =25℃	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>		50	Α
I <sub>D</sub> @T <sub>C</sub> =100℃	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	3	37	
I <sub>D</sub> @T <sub>A</sub> =25℃	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	14	12	А
I <sub>D</sub> @T <sub>A</sub> =70°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	11.4	9.7	А
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	100		А
EAS	Single Pulse Avalanche Energy <sup>3</sup>	50		mJ
I <sub>AS</sub>	Avalanche Current	14		А
P <sub>D</sub> @T <sub>C</sub> =25℃	Total Power Dissipation <sup>4</sup>	26		W
P <sub>D</sub> @T <sub>A</sub> =25℃	Total Power Dissipation <sup>4</sup>	2.5	1.6	W
T <sub>STG</sub>	Storage Temperature Range	-55 t	-55 to 150	
TJ	Operating Junction Temperature Range -55 to 150		$^{\circ}$	

### **Thermal Data**

Symbol	Parameter	Тур.	Max.	Unit
$R_{ heta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>		70	°C/W
$R_{ heta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup> (t ≤10s)		50	°C/W
$R_{ heta JC}$	Thermal Resistance Junction-Case <sup>1</sup>		4.7	°C/W



# Electrical Characteristics (T<sub>J</sub>=25 ℃, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	30			V
$\triangle BV_{DSS}/\triangle T_{J}$	BVDSS Temperature Coefficient	Reference to 25℃ , I <sub>D</sub> =1mA		0.024		V/°C
В	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V , I <sub>D</sub> =15A		6.7	8.5	m()
R <sub>DS(ON)</sub>	Static Dialii-Source On-Resistance	V <sub>GS</sub> =4.5V , I <sub>D</sub> =10A		8.2	11	mΩ
$V_{GS(th)}$	Gate Threshold Voltage		1.5	1.8	2.5	V
$\triangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	V <sub>GS</sub> -V <sub>DS</sub> , I <sub>D</sub> -250uA		-3.5		mV/℃
	Drain Source Leakage Current	V <sub>DS</sub> =24V , V <sub>GS</sub> =0V , T <sub>J</sub> =25℃			1	— uA
I <sub>DSS</sub>	Drain-Source Leakage Current	$V_{DS}$ =24V , $V_{GS}$ =0V , $T_{J}$ =55 $^{\circ}$ C			5	
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS}$ = $\pm 20 V$ , $V_{DS}$ = $0 V$			±100	nA
gfs	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =30A		40		S
$R_g$	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		1.0	1.5	Ω
Qg	Total Gate Charge (4.5V)	V <sub>DS</sub> =15V , V <sub>GS</sub> =10V , I <sub>D</sub> =15A		10	12	
$Q_gs$	Gate-Source Charge			3.5	4.1	nC
Q <sub>gd</sub>	Gate-Drain Charge			4.2	4.7	
$T_{d(on)}$	Turn-On Delay Time			9	17	
T <sub>r</sub>	Rise Time	$V_{DD}$ =15V , $V_{GS}$ =10V , $R_G$ =6 $\Omega$ $I_D$ =1A , $R_L$ =15 $\Omega$		11	23	
T <sub>d(off)</sub>	Turn-Off Delay Time			29	52	ns
T <sub>f</sub>	Fall Time			7	12	1
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =15V , V <sub>GS</sub> =0V , f=1MHz		1200	1400	
C <sub>oss</sub>	Output Capacitance			185	220	pF
C <sub>rss</sub>	Reverse Transfer Capacitance			113	140	

#### **Guaranteed Avalanche Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
EAS	Single Pulse Avalanche Energy <sup>5</sup>	V <sub>DD</sub> =25V , L=0.1mH , I <sub>AS</sub> =20A	18			mJ

## **Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current <sup>1,6</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			20	Α
I <sub>SM</sub>	Pulsed Source Current <sup>2,6</sup>				100	Α
$V_{SD}$	Diode Forward Voltage <sup>2</sup>	$V_{GS}$ =0V , $I_{S}$ =2A , $T_{J}$ =25 $^{\circ}$ C			1	V
t <sub>rr</sub>	Reverse Recovery Time	IF=15A,dIsp/dt=100A/µs,T <sub>J</sub> =25°C		15		nS
Qrr	Reverse Recovery Charge			7		nC

#### Note:

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper,t<10sec.
- 2.The data tested by pulsed , pulse width  $\leq$  300us , duty cycle  $\leq$  2%
- 3.The EAS data shows Max. rating . The test condition is  $V_{DD}$ =25V, $V_{GS}$ =10V,L=0.1mH, $I_{AS}$ =20A
- 5.The Min. value is 100% EAS tested guarantee.
- 6. The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.



## **Typical Characteristics**

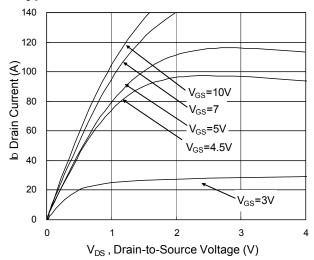


Fig.1 Typical Output Characteristics

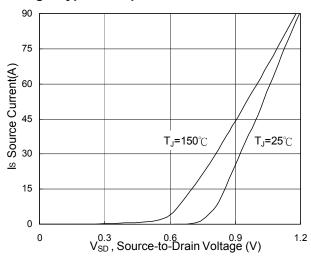


Fig.3 Forward Characteristics of Reverse

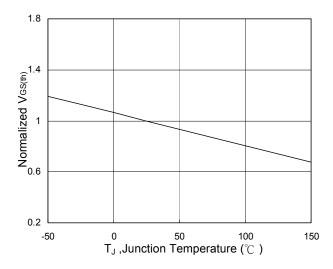


Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$ 

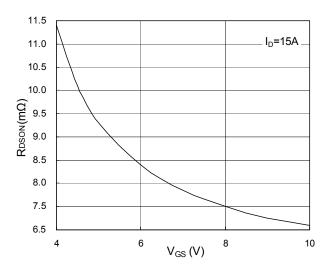


Fig.2 On-Resistance vs. Gate-Source

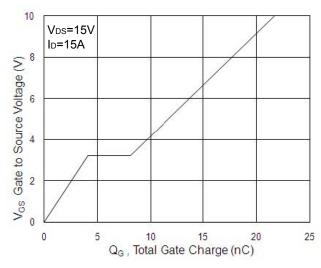


Fig.4 Gate-Charge Characteristics

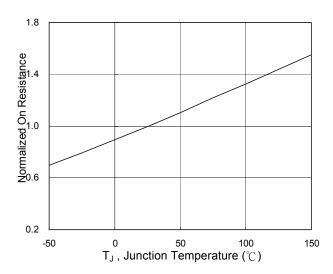
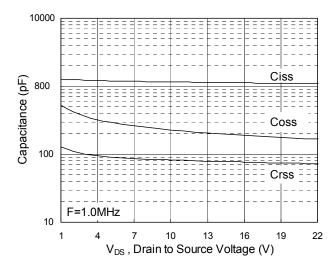


Fig.6 Normalized R<sub>DSON</sub> vs. T<sub>J</sub>





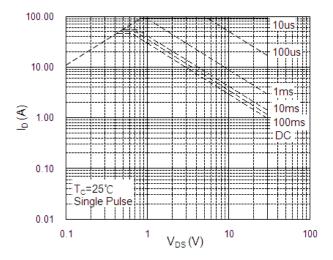


Fig.7 Capacitance

Fig.8 Safe Operating Area

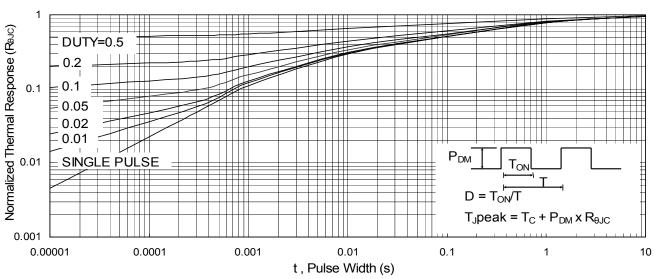


Fig.9 Normalized Maximum Transient Thermal Impedance

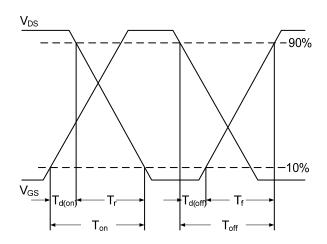


Fig.10 Switching Time Waveform

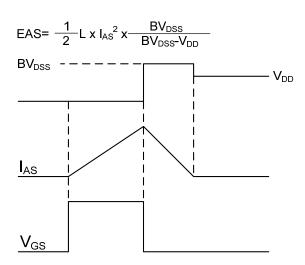


Fig.11 Unclamped Inductive Switching Waveform



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